

## CLAIMS

What is claimed is:

1           1. A device enclosure comprising:  
2           a thermo-siphon device embedded in an enclosure skin.

1           2. The device of claim 1, wherein the device is an electronic  
2           device.

1           3. The device of claim 2, wherein the device enclosure is a  
2           computer chassis.

1           4. The device of claim 1, wherein the device is a non-  
2           electronic device.

1           5. The device of claim 1, wherein the thermo-siphon device is  
2           a heat pipe.

1           6. The device of claim 1, wherein the thermo-siphon device is  
2           a strip of a high efficiency conduit material.

1           7. The device of claim 1, wherein the thermo-siphon device is  
2           an integral part of the skin.

1           8. The device of claim 7, wherein the thermo-siphon device is  
2           embedded in the skin during the manufacturing process of the skin.

1           9. The device of claim 1, wherein the skin is fabricated from a  
2           metallic material.

1 10. The device of claim 1, wherein the thermo-siphon device is  
2 embedded in a skin cavity.

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11. The device of claim 10, wherein the cavity is created during  
2 a fabrication process of the skin.

1 12. The device of claim 1, wherein the skin partially encloses  
2 the thermo-siphon device.

1 13. The device of claim 12, wherein a portion of the thermo-  
2 siphon device is exposed to an interior of the enclosure.

1 14. The device of claim 12, wherein a portion of the thermo-  
2 siphon device is exposed to a heat sink.

1 15. The device of claim 1, wherein the thermo-siphon device is  
2 not an integral part of the skin.

1 16. The device of claim 15, wherein the thermo-siphon device  
2 can be inserted and removed from a skin cavity by accessing the interior  
3 of the enclosure.

1 17. The device of claim 1, wherein the thermo-siphon device is  
2 secured to a skin cavity through the means selected from the group  
3 consisting of a support provided by skin cavity walls, a thermal epoxy,  
4 and an interference fit with the skin cavity.

1 18. The device of claim 1, wherein a metallic plate interfaces a  
2 heat source with the thermo-siphon device.

1 19. A system comprising:  
2 a housing including a thermo-siphon device embedded in a  
3 housing skin.

*Cont Sub-A!*   
1 20. The system of claim 19, wherein the thermo-siphon device  
2 is a heat pipe.

1 21. The system of claim 19, wherein the thermo-siphon device  
2 is a strip of high efficiency conduit material.

1 22. The system of claim 19, wherein the housing is a computer  
2 chassis.

1 23. The system of claim 19, wherein the thermo-siphon device  
2 is an integral part of the housing skin.

1 24. A computer chassis comprising:  
2 a thermo-siphon device embedded in a computer chassis  
3 skin.

*Cont Sub-A!*   
1 25. The computer chassis of claim 24, wherein the thermo-  
2 siphon device is a heat pipe.

1 26. The computer chassis of claim 24, wherein the computer  
2 chassis is a notebook computer base.

1 27. The computer chassis of claim 24, wherein the thermo-  
2 siphon device is an integral part of the skin.

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28. The computer chassis of claim 27, wherein the thermo-siphon device is embedded in the skin during the manufacturing process of the skin.